No.: FMC-K-HTS-0001 /9

Date: 2024. 12. 24

# Data sheet

Title: CHIP FUSE; RECTANGULAR TYPE

Style: FMC10, 16

# RoHS COMPLIANCE ITEM Halogen and Antimony Free

Note: •Stock conditions

Temperature:  $+5^{\circ}C \sim +35^{\circ}C$ Relative humidity:  $25\% \sim 75\%$ 

The period of guarantee: Within 2 year from shipmen t by the company.

Solderability shall be satisfied.

- Product specification contained in this data sheet are subject to change at any time without notice
- •If you have any questions or a Purchasing Specification for any quality Agreement is necessary, please contact our sales staff.



Hokkaido Research Center Approval by: T. Sannomiya Drawing by: M. Shibuya AYA OHM

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#### 1. Scope

1.1 This data sheet covers the detail requirements for chip fuses; rectangular type, style of FMC10, 16.

# 1.2 Applicable documents

UL248-1-2000 Low-Voltage Fuses-Part1: General Requirements

UL248-14-2000 Low-Voltage Fuses-Part14: Supplemental Fuses

CSA C22.2 No.248.1–2000 Low-Voltage Fuses-Part1: General Requirements

CSA C22.2 No.248.14-2000 Low-Voltage Fuses-Part14: Supplemental Fuses

#### 2. Classification

Type designation shall be the following form.

# 4 Optional code

Symbol	Optional code
AB	
WB	Standard
WH	

5 Packaging form

TH	Denertoning
TP	Paper taping

# 3. Safety standard approval

- UL248-1 and UL248-14
- CSA C22.2, No. 248.1-00 and CSA C22.2, No. 248.14-00

The file number to be designated by UL and C-UL shall be as follows: E176847

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# 4. Rating

The ratings shall be in accordance with Table–1.

# 4.1 Optional code: AB

Table-1(1)

	Rated current		Internal resistance value	Rated	Breaking	Time / cu	Time / current characteristic	
Style	Symbol	(A)	Marking symbol	(m $\Omega$ max.)	voltage (V)	capacity (A)	Current	Pre-arcing time
	501	0.5	F	240			100%	4 h min. 5 s max. 0.2 s max.
	751	0.75	Α	140		DC24 35 200%		
	102	1.0	L	95	DC24			
FMC10	132	1.25	М	73				
I WIC IO	152	1.5	Н	60	DO24		300%	
	202	2.0	S	41			00070	
	252	2.5	Т	32				
	302	3.0	R	25				

# 4.2 Optional code: WB

Table-1(2)

Style	Rated current		ent	Internal resistance value	Rated	Breaking	Time / current characteristic	
	Symbol	(A)	Marking symbol	(m $\Omega$ max.)	voltage (V)	capacity (A)	Current	Pre-arcing time
	501	0.5	F	260				
	751	0.75	Α	140				
	102	1.0	L	110				
	132	1.25	М	80	DC32	25	100% 200% 300%	4 h min. 5 s max. 0.2 s max.
FMC16	152	1.5	Н	65				
FIVIC 16	202	2.0	S	45	DC32	35		
	252	2.5	Т	32			30070	0.2 3 max.
	302	3.0	R	26				
	402	4.0	Х	18				
	502	5.0	Υ	14				

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# 4.3 Optional code: WH

Table-1(3)

	R	ated curr	ent	Internal resistance value	Rated	Breaking	Time / current characteristic	
Style	Symbol (A) Marking symbol $(m\Omega \text{ max.})$ voltage capacity (V) (A)		Current	Pre-arcing time				
	501	0.5	<u>F</u>	250				
FMC10	751	0.75	<u>A</u>	150				
	102	1.0	<u>L</u>	100				
	132	1.25	M	70				
	152	1.5	<u>H</u>	60			100%	4 h min.
	202	2.0	<u>S</u>	40	DC24	35	200%	5 s max.
	252	2.5	T	30			300%	0.2 s max.
	302	3.0	<u>R</u>	25				
	322	3.15	<u>U</u>	24				
	402	4.0	<u>X</u>	18				
	502	5.0	<u>Y</u>	14				
	501	0.5	OF	400				
	631	0.63	OI	300				
	751	0.75	OA	210				
	801	0.8	OK	180				
	102	1.0	OL	115				
	132	1.25	OM	90			100%	4 h min.
FMC16	152	1.5	OH	70	DC32	35	200%	5 s max.
1 IVIC 10	162	1.6	ON	60	DC32	33	300%	0.2 s max.
	202	2.0	OS	50			30070	0.2 3 max.
	252	2.5	OT	37				
	302	3.0	OR	28				
	322	3.15	OU	26				
	402	4.0	OX	18				
	502	5.0	OY	14				

4.4 Working temperature range: -55 to +125(°C)

# 5. Packaging form

The standard packaging form shall be in accordance with Table-2.

Table-2

Symbol	Packaging form		Standard packaging quantity / units	Application
TH	Paper taping	8mm width, 2mm pitches	10,000 pcs.	FMC10
TP	Paper taping	8mm width, 4mm pitches	5,000 pcs.	FMC16

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# 6. Dimensions

6.1 The resistor shall be of the design and physical dimensions in accordance with Figure-1 and Table-3.

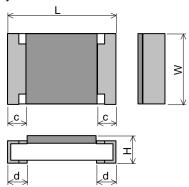


Figure-1

Table–3 Unit: mm

Style	Optional code	L	W	Н	С	d
EMC10	WH	1.010.05	0.5±0.05	0.35±0.05	0.2±0.10	0.25±0.10
FMC10	AB	1.0±0.05		0.38±0.05		
FMC16	WB,WH	1.6±0.1	0.8 +0.15 -0.05	0.45±0.10	0.3±0.15	0.3±0.1

# 6.2 Net weight (Reference)

Style	Net weight(mg)
FMC10	0.6
FMC16	2

# 7. Marking

The Marking symbol of Sub-clause 4.1 shall be marked on over coat side.

# (Example)

Style	Optional code	Marking symbol	Content
FMC10	AB	S	FMC10 202 AB
FMC10	WH	<u>s</u>	FMC10 202 WH
FMC16	WB	S	FMC16 202 WB
FMC16	WH	OS	FMC16 202 WH

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#### 8. Performance

8.1 Unless otherwise specified, the standard range of atmospheric conditions for tests is as follows;

Ambient temperature: 5 °C to 35 °C, Relative humidity: 45 % to 85 %, Air presser: 86 kPa to 106 kPa

If there is any doubt the results, measurements shall be made within the following:

Ambient temperature: 20 °C  $\pm$  2 °C, Relative humidity: 60 % to 70 %, Air presser: 86 kPa to 106 kPa

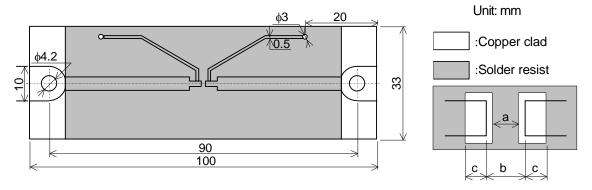
8.2 The performance shall be satisfied in Table-4.

Table 4(1)

Nic	Test items Condition of test Performance requirements				
No.		Condition of test			
1	Temperature rise	The fuse shall be mounted on the test substrate as shown in Figure–2.  Measurement temp.: 10 °C to 30 °C  Test current: Rated current  The temperature at the hottest point on the surface of the fuse shall be measured after temperature equilibrium has been attained.	75 °C max.		
2	Time / current characteristic	The fuse shall be mounted on the test substrate as	Current	Pre-arcing time	
		shown in Figure–2.  Test current shall be applied for continuously.	100% 200% 300%	4 h min. 5 s. max. 0.2 s max.	
3	Terminal bond strength of	<u>JIS C 60068-2-21 Ue1</u>		internal resistance:	
	the face plating	The fuse shall be mounted on the test substrate as shown in Figure–2. Bending value: $3 \text{ mm}(\text{Among the fulcrums: } 90 \text{ mm})$ Duration: $10 \text{ s} \pm 1 \text{ s}$	±10% No evidence of mechan damage.		
4	Resistance to soldering heat	Test by a piece. Temp. of solder bath: $260 ^{\circ}\text{C} \pm 5 ^{\circ}\text{C}$ Immersion time: $10  \text{s} \pm 1  \text{s}$ After immersion into solder, leaving the room temp. for 1h or more, and then measure the internal resistance.  • Reflow soldering Pre–heating: $150 ^{\circ}\text{C} \sim 180 ^{\circ}\text{C}$ , $120  \text{s}$ max. Peak: $260 ^{\circ}\text{C} \pm 5 ^{\circ}\text{C}$ , $10  \text{s}$ max. Reflow cycle: $2  \text{times}$ After immersion into solder, leaving the room temp. for 1h or more, and then measure the internal resistance.	Change of internal resistance: ±10%  No evidence of appearance damage		
5	Solderability	<u>JIS C 60068-2-58</u> Test by a piece Flux: Rosin–Methanol Temp. of solder: bath: 235 °C $\pm$ 5 °C Immersion time: 2 s $\pm$ 0.5 s	The surface of terminal immer shall be min. of 95 % covered a new coating of solder.		
6	Rapid change temperature	JIS C 60068-2-14 Na The fuse shall be mounted on the test substrate as shown in Figure–2. Lower temperature: –55 °C Upper temperature: +125 °C Duration of exposure at each temperature: 30 min. Number of cycles: 5 cycles	Change of ±10% No evide damage	internal resistance: ence of appearance	

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#### 9. Test substrate



Style	а	b	С
FMC10	0.3	0.6	0.65
FMC16	0.6	1.0	0.5

# Figure-2 FMC TEST SUBSTRATE

Remark 1). Material: Epoxide woven glass

Thickness: 1. 6mm Thickness of copper clad: 0. 035mm

# 10. Taping

10.1 Applicable documents JIS C 0806-3: 2014, EIAJ ET-7200C: 2010

10.2 Taping dimensions

10.2.1 Paper taping (8mm width, 2mm pitches)

Taping dimensions shall be in accordance with Figure-3 and Table-5.

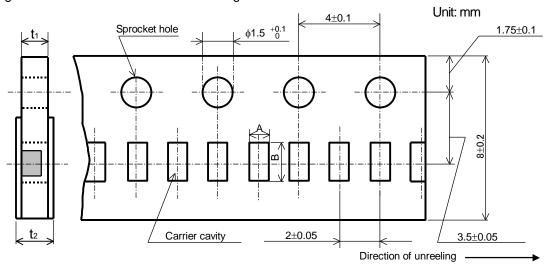


Figure-3

	Unit: mm			
Style	Α	В	<b>t</b> 1	t <sub>2</sub>
FMC10	0.65 <sup>+0.05</sup> <sub>-0.10</sub>	1.15 <sup>+0.05</sup> <sub>-0.10</sub>	$0.4 \pm 0.05$	0.5max.

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# 10.2.2 Paper taping (8mm width, 4mm pitches)

Taping dimensions shall be in accordance with Figure-4 and Table-6.

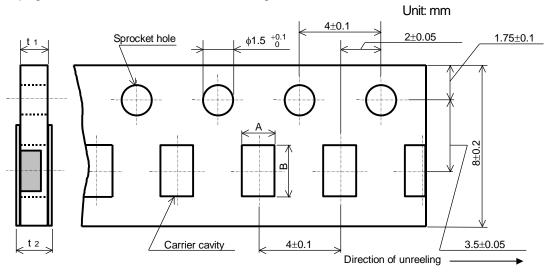
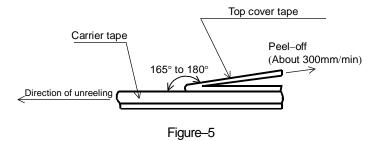


Figure-4
Table-6 Unit: mm

Style A B t<sub>1</sub> t<sub>2</sub>

FMC16 1.15±0.15 1.9±0.2 0.6±0.1 0.8 max.

- 1). The cover tapes shall not cover the sprocket holes.
- 2). Tapes in adjacent layers shall not stick together in the packing.
- 3). Components shall not stick to the carrier tape or to the cover tape.
- 4). Pitch tolerance over any 10 pitches ±0.2mm.
- 5). The peel strength of the top cover tape shall be with in 0.1N to 0.5N on the test method as shown in the following Figure–5.
- 6). When the tape is bent with the minimum radius for 25 mm, the tape shall not be damaged and the components shall maintain their position and orientation in the tape.
- In no case shall there be two or more consecutive components missing.The maximum number of missing components shall be one or 0.1%, whichever is greater.
- 8). The fuses shall be faced to upward at the over coating side in the carrier cavity.

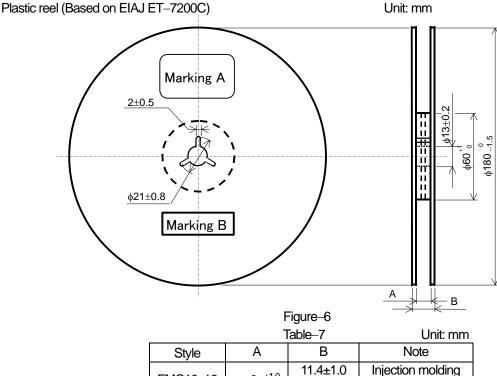


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#### 10.3 Reel dimension

Reel dimensions shall be in accordance with the following Figure–6 and Table–7.



11.4±1.0 Injection molding 9 +1.0 FMC10, 16 13±1.0 Vacuum forming

Note: Marking label shall be marked on a place of Marking A or two place of marking A and B.

# 10.4 Leader and trailer tape.

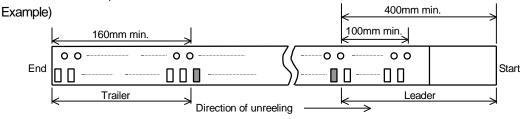


Figure-7

# 11. Marking on package

The label of a minimum package shall be legibly marked with follows.

# 11.1 Marking A

- (1) Classification (Style, Rated current, Optional code, Packaging form) (2) Quantity (3) Lot number
- (4) Manufacturer's name or trade mark (5) UL and /or C-UL recognized component mark (6) Others
- 11.2 Marking B (KAMAYA Control label)

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# 12. Recommended Derating for Rated Current

This fuse will recommend use by the current reduction value according to the following derating curve.

Nominal Derating

Nominal Derating ≤ 75% of Rated Current

\*FMC10 Optional code: WH, Rated current ≥ 3.15A: Nominal Derating ≤ 70% of Rated Current

Temperature Derating

Please refer to the following graph regarding the current derating value for ambient temperature.

Ex.) If FMC16 202WH (Rated Current 2.0A) is used under ambient temperature 70°C,

Kamaya recommends, less than the current value derated as below,

Rated Current: 2.0A × (Nominal Derating: 75% × Temperature Derating: 80%) = 1.2A

# **Derating curve**

